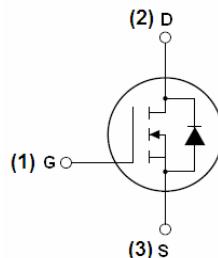


**N-Channel Enhancement Mode Power MOSFET**
**Description**

The UMW IRL540N uses advanced trench technology and design to provide excellent  $R_{DS(ON)}$  with low gate charge. It can be used in a wide variety of applications.

**General Features**

- $V_{DS} = 100V, I_D = 30A$
- $R_{DS(ON)} < 28m\Omega @ V_{GS}=10V$  (Typ:24 mΩ)


**Schematic diagram**

- Special process technology for high ESD capability
- High density cell design for ultra low  $R_{DS(on)}$
- Fully characterized avalanche voltage and current
- Good stability and uniformity with high  $E_{AS}$
- Excellent package for good heat dissipation


**TO-220-3L top view**
**Application**

- Power switching application
- Hard switched and high frequency circuits
- Uninterruptible power supply

**Absolute Maximum Ratings ( $T_c=25^\circ C$  unless otherwise noted)**

Symbol	Parameter	Limit	Unit
$V_{DS}$	Drain-Source Voltage	100	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D$	Drain Current-Continuous	30	A
$I_D (100^\circ C)$	Drain Current-Continuous( $T_c=100^\circ C$ )	21	A
$I_{DM}$	Pulsed Drain Current	70	A
$P_D$	Maximum Power Dissipation	75	W
	Derating factor	0.5	W/°C
$E_{AS}$	Single pulse avalanche energy <sup>(Note 5)</sup>	256	mJ
$T_J, T_{STG}$	Operating Junction and Storage Temperature Range	-55 To 175	°C

**Thermal Characteristic**

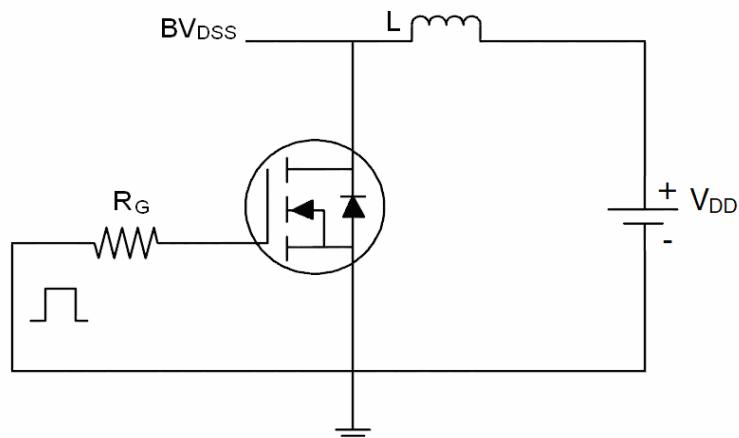
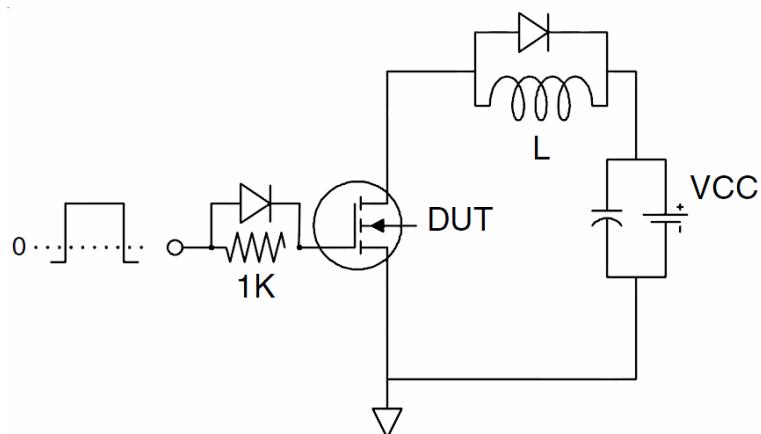
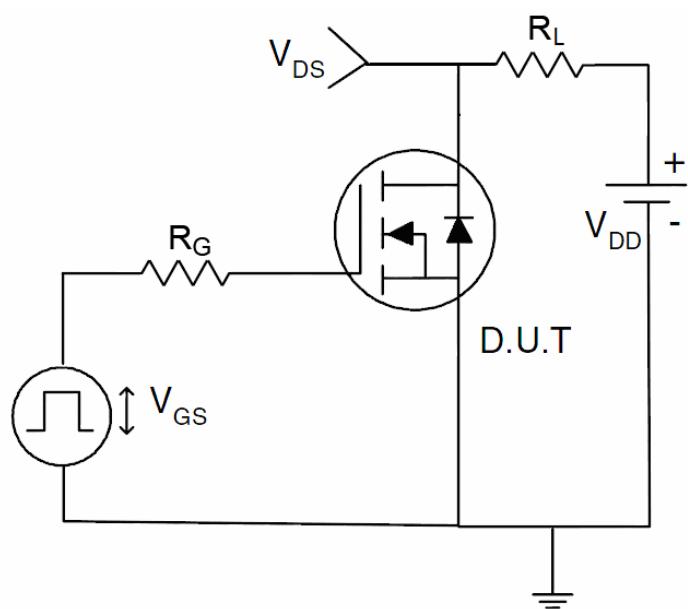
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case <sup>(Note 2)</sup>	2.0	$^{\circ}\text{C}/\text{W}$
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**Electrical Characteristics ( $T_c=25^{\circ}\text{C}$  unless otherwise noted)**

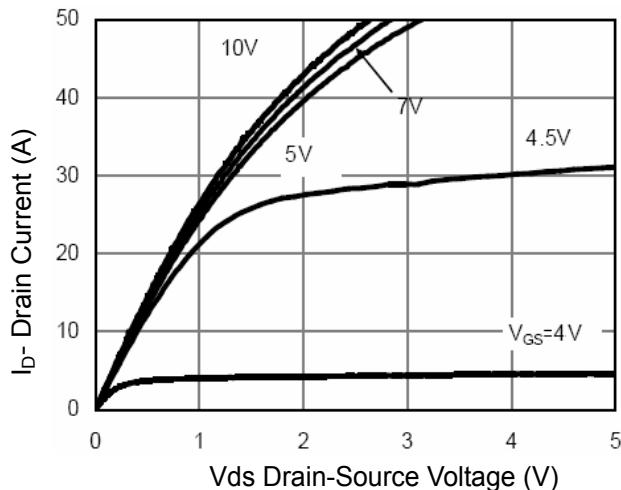
Symbol	Parameter	Condition	Min	Typ	Max	Unit
<b>Off Characteristics</b>						
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=250\mu\text{A}$	100	110	-	V
$I_{\text{DS}(\text{SS})}$	Zero Gate Voltage Drain Current	$V_{\text{DS}}=100\text{V}, V_{\text{GS}}=0\text{V}$	-	-	1	$\mu\text{A}$
$I_{\text{GSS}}$	Gate-Body Leakage Current	$V_{\text{GS}}=\pm 20\text{V}, V_{\text{DS}}=0\text{V}$	-	-	$\pm 100$	nA
<b>On Characteristics</b> <sup>(Note 3)</sup>						
$V_{\text{GS}(\text{th})}$	Gate Threshold Voltage	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=250\mu\text{A}$	2	3	4	V
$R_{\text{DS}(\text{ON})}$	Drain-Source On-State Resistance	$V_{\text{GS}}=10\text{V}, I_{\text{D}}=15\text{A}$	-	24	28	$\text{m}\Omega$
$g_{\text{FS}}$	Forward Transconductance	$V_{\text{DS}}=5\text{V}, I_{\text{D}}=10\text{A}$	-	15	-	S
<b>Dynamic Characteristics</b> <sup>(Note 4)</sup>						
$C_{\text{iss}}$	Input Capacitance	$V_{\text{DS}}=25\text{V}, V_{\text{GS}}=0\text{V}, F=1.0\text{MHz}$	-	2000	-	PF
$C_{\text{oss}}$	Output Capacitance		-	300	-	PF
$C_{\text{rss}}$	Reverse Transfer Capacitance		-	250	-	PF
<b>Switching Characteristics</b> <sup>(Note 4)</sup>						
$t_{\text{d}(\text{on})}$	Turn-on Delay Time	$V_{\text{DD}}=50\text{V}, R_{\text{L}}=5\Omega$ $V_{\text{GS}}=10\text{V}, R_{\text{GEN}}=3\Omega$	-	7	-	nS
$t_{\text{r}}$	Turn-on Rise Time		-	7	-	nS
$t_{\text{d}(\text{off})}$	Turn-Off Delay Time		-	29	-	nS
$t_{\text{f}}$	Turn-Off Fall Time		-	7	-	nS
$Q_g$	Total Gate Charge	$V_{\text{DS}}=50\text{V}, I_{\text{D}}=18\text{A}, V_{\text{GS}}=10\text{V}$	-	39	-	nC
$Q_{\text{gs}}$	Gate-Source Charge		-	8	-	nC
$Q_{\text{gd}}$	Gate-Drain Charge		-	12	-	nC
<b>Drain-Source Diode Characteristics</b>						
$V_{\text{SD}}$	Diode Forward Voltage <sup>(Note 3)</sup>	$V_{\text{GS}}=0\text{V}, I_{\text{S}}=20\text{A}$	-	-	1.2	V
$I_{\text{S}}$	Diode Forward Current <sup>(Note 2)</sup>	-	-	-	30	A
$t_{\text{rr}}$	Reverse Recovery Time	$T_J = 25^{\circ}\text{C}, IF = 18\text{A}$ $dI/dt = 100\text{A}/\mu\text{s}$ <sup>(Note 3)</sup>	-	32	-	nS
$Q_{\text{rr}}$	Reverse Recovery Charge		-	53	-	nC
$t_{\text{on}}$	Forward Turn-On Time	Intrinsic turn-on time is negligible (turn-on is dominated by LS+LD)				

**Notes:**

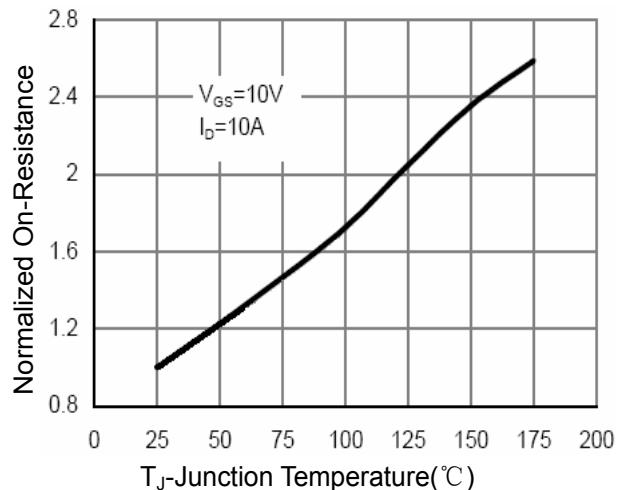
1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board,  $t \leq 10$  sec.
3. Pulse Test: Pulse Width  $\leq 300\mu\text{s}$ , Duty Cycle  $\leq 2\%$ .
4. Guaranteed by design, not subject to production
5. EAS Condition :  $T_j=25^{\circ}\text{C}, V_{\text{DD}}=50\text{V}, V_{\text{G}}=10\text{V}, L=0.5\text{mH}, R_g=25\Omega, I_{\text{AS}}=32\text{A}$

**Test Circuit****1) E<sub>AS</sub> Test Circuit****2) Gate Charge Test Circuit****3) Switch Time Test Circuit**

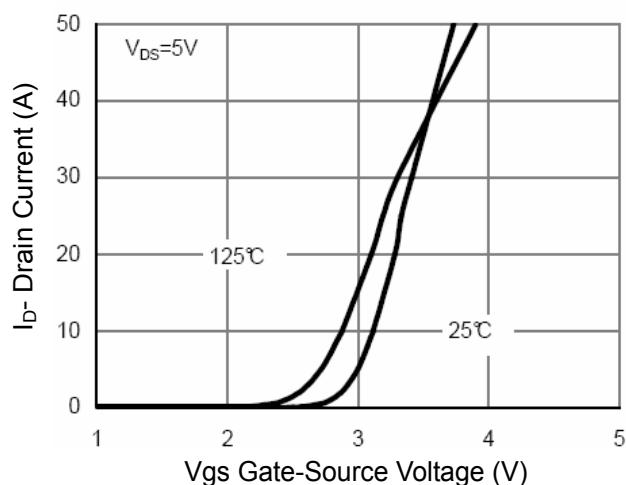
**Typical Electrical and Thermal Characteristics (Curves)**



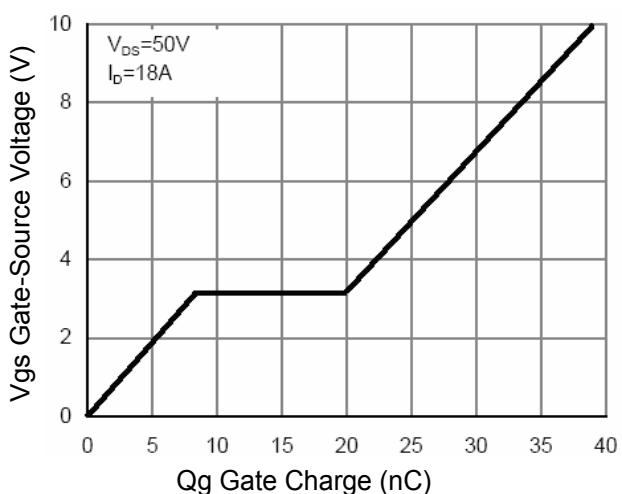
**Figure 1 Output Characteristics**



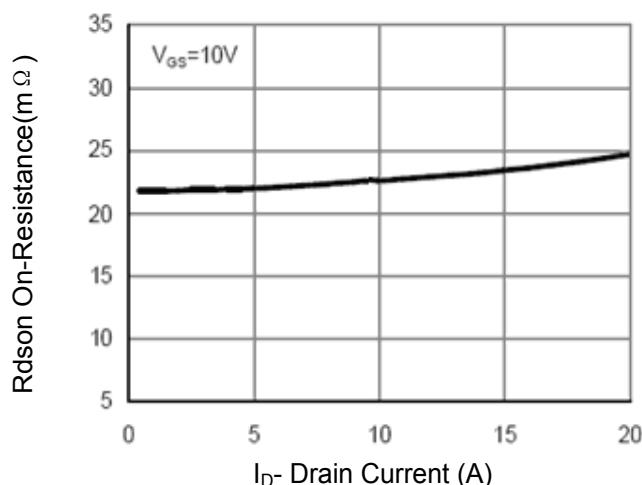
**Figure 4  $R_{DS(on)}$ -Junction Temperature**



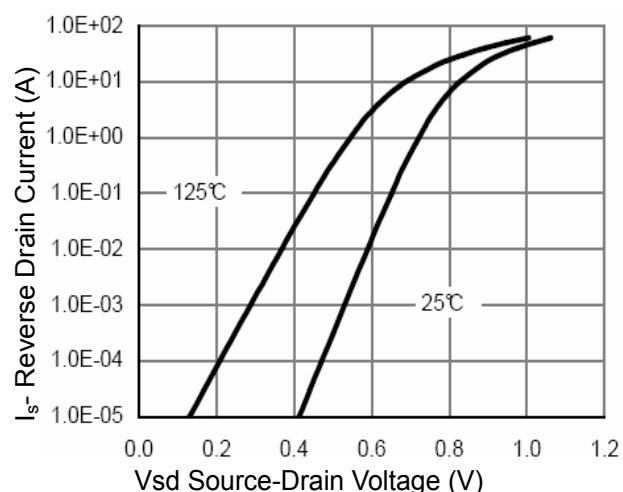
**Figure 2 Transfer Characteristics**



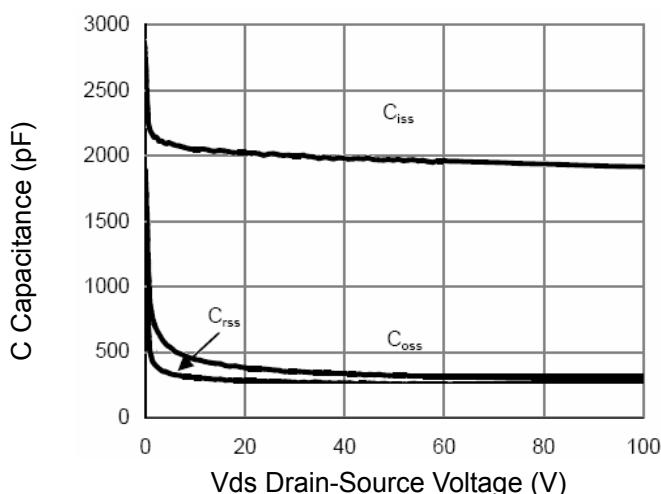
**Figure 5 Gate Charge**



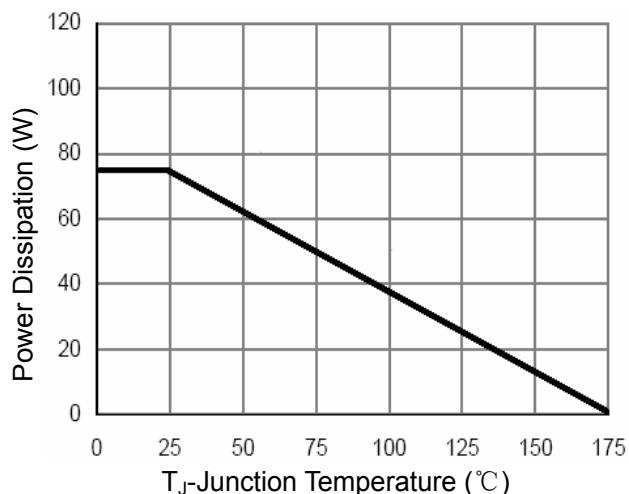
**Figure 3  $R_{DS(on)}$ - Drain Current**



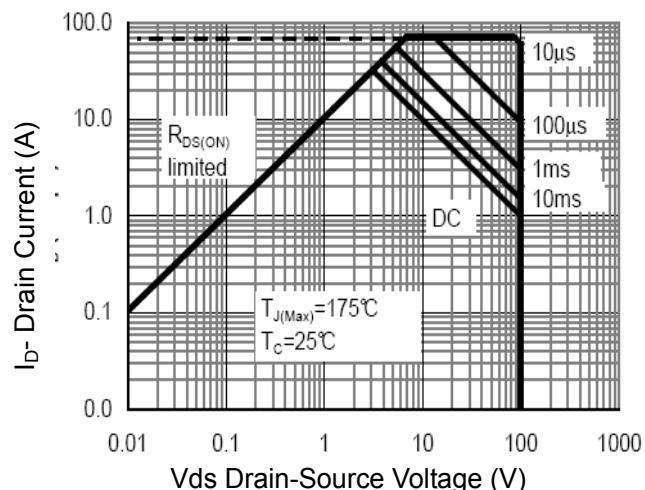
**Figure 6 Source- Drain Diode Forward**



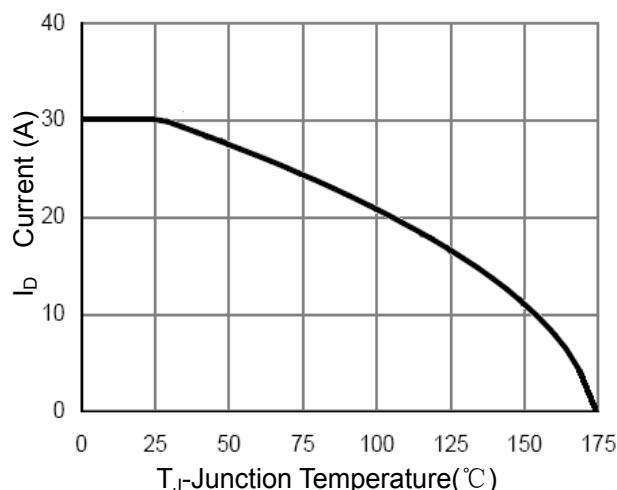
**Figure 7 Capacitance vs Vds**



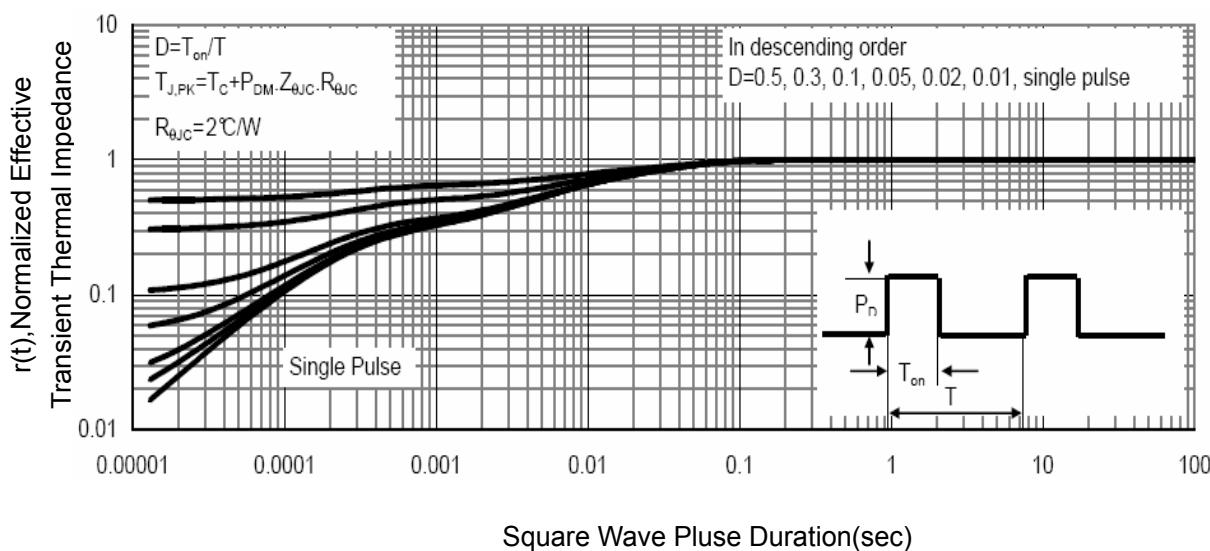
**Figure 9 Power De-rating**



**Figure 8 Safe Operation Area**

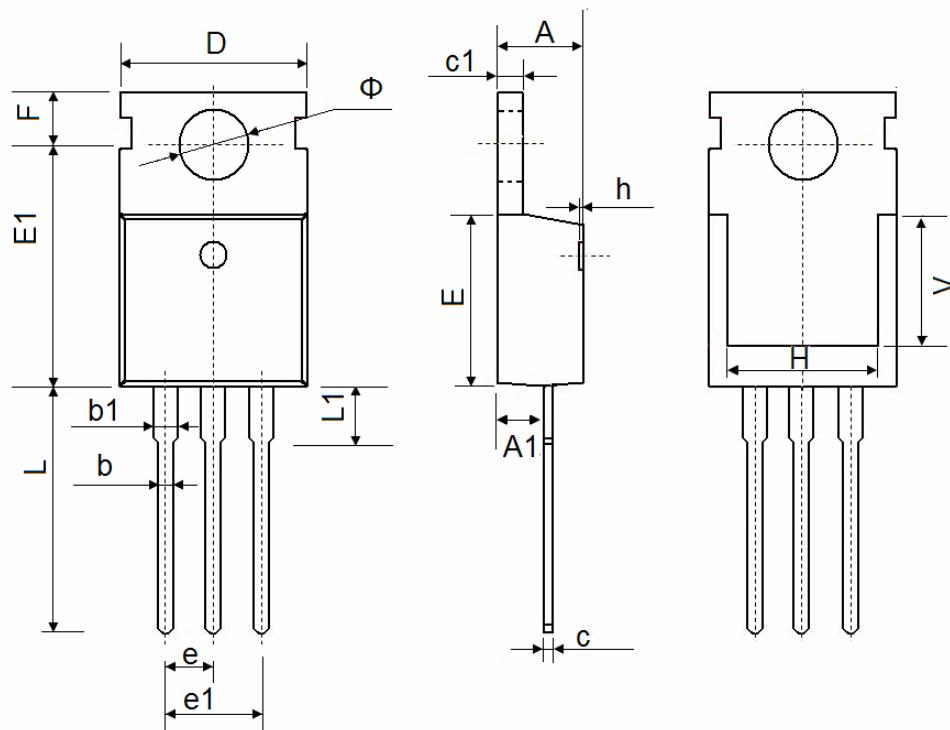


**Figure 10 ID Current- Junction Temperature**

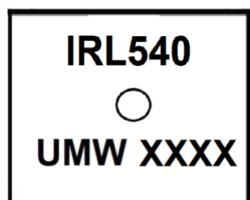


**Figure 11 Normalized Maximum Transient Thermal Impedance**

## TO-220-3L Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	4.400	4.600	0.173	0.181
A1	2.250	2.550	0.089	0.100
b	0.710	0.910	0.028	0.036
b1	1.170	1.370	0.046	0.054
c	0.330	0.650	0.013	0.026
c1	1.200	1.400	0.047	0.055
D	9.910	10.250	0.390	0.404
E	8.9500	9.750	0.352	0.384
E1	12.650	12.950	0.498	0.510
e	2.540 TYP.		0.100 TYP.	
e1	4.980	5.180	0.196	0.204
F	2.650	2.950	0.104	0.116
H	7.900	8.100	0.311	0.319
h	0.000	0.300	0.000	0.012
L	12.900	13.400	0.508	0.528
L1	2.850	3.250	0.112	0.128
V	7.500 REF.		0.295 REF.	
Φ	3.400	3.800	0.134	0.150

**Marking****Ordering information**

Order code	Package	Baseqty	Deliverymode
UMW IRL540N	TO-220	1000	Tube and box